Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	70	(US-20030080437-$).did. or (US-4811081-$ or US-5034245-$ or US-5502889-$ or US-5518964-$ or US-5604379-$ or US-5657104-$ or US-5657206-$ or US-5677576-$ or US-5749997-$ or US-5813870-$ or US-5819406-$ or US-5846853-$ or US-5861661-$ or US-5886415-$ or US-5918113-$ or US-5945729-$ or US-5949142-$ or US-5990563-$ or US-6008072-$ or US-6011315-$ or US-6028365-$ or US-6031590-$ or US-6060782-$ or US-6080931-$ or US-6103553-$ or US-6121688-$).did. or (US-6133637-$ or US-6137183-$ or US-6140707-$ or US-6147311-$ or US-6175151-$ or US-6194780-$ or US-6204564-$ or US-6228687-$ or US-6239384-$ or US-6262473-$ or US-6284086-$ or US-6285085-$ or US-6307254-$ or US-6323552-$ or US-6335568-$ or US-6355504-$ or US-6356333-$ or US-6383840-$ or US-6409866-$ or US-6410364-$ or US-6410366-$ or US-6414382-$ or US-6417029-$ or US-6420664-$ or US-6429453-$ or US-6448634-$ or US-6458236-$).did. or (US-6458609-$ or US-6461890-$ or US-6468830-$ or US-6483718-$ or US-6489687-$ or US-6507095-$ or US-6514560-$ or US-6518091-$ or US-6521483-$ or US-6521995-$ or US-6528343-$ or US-6551918-$ or US-6620652-$ or US-6784555-$ or US-6919627-$ or US-RE38053-$).did.	US-PGPUB; USPAT	OR	ON	2005/12/16 09:00
L2	0	("6919627").URPN.	USPAT	OR	ON	2005/12/16 09:06
L3	5	("20030054162" | "20030141582" | "5323060" | "6005778" | "6388313").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:10
L4	1	09/954262	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L5	6	("5034245").URPN.	USPAT	OR	ON	2005/12/16 09:22

L6	13	("3391455" | "3951063" | "4049844" | "4075049" | "4327124" | "4401686" | "4469777" | "4572764" | "4654752" | "4807021" | "4814090" | "4863757").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:23
L7	5	"6352775"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L8	28	"6410415"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L9	3	"6403711"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L10	4	"5326845"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L11	61	"4491553"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L12	101	7 8 9 10 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:26
L13	101	12 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:26

L14	84	12 and (filler particle microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:32
L15	687442	(chip die semiconductor) with (substrate carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L16	11188	adhesive near4 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L17	1482	15 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L18	8877	adhesive near3 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L19	474624	(chip die semiconductor) near3 (substrate carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:34
L20	936	19 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:34
L21	9388	(partical filler microparticle) near3 diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35

L22	105	20 and 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35
L23	103	22 not 1 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35
L24	0	("6635956").URPN.	USPAT	OR	ON	2005/12/16 09:47
L25	2	("6001671" | "6459549").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:47

L2	8877	adhesive near3 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L3	242	2 with diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
L4	83	3 and (chip die ((semiconductor electronic optical) near1 (element device)) with (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:19
L5	189	4not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:05
L6	80	4 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:05
L7	83	3 and (chip die ((semiconductor electronic optical) near1 (element device)) same (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:20
L8	87	3 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
L9	4	8 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:20

L10	3185	2 and diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
L11	1215	10 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:22
L12	594	2 same diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L13	177	12 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L14	90	13 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:22
L15	26389	adhesive with (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L16	1556	15 same diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L17	422	16 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:30

L18	245	17 not 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:30